

# **Power line chokes**

Current-compensated D core double chokes 250 V AC, 3.3 ... 68 mH, 0.7 ... 4.6 A, +40 °C / +60 °C

Series/Type: B82734R/W Date: December 2016

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B82734R/W

## **Power line chokes**

**Current-compensated D core double chokes** 

### Rated voltage 250 V AC Rated inductance 3.3 ... 68 mH

Rated current 0.7 ... 4.6 A / +40 °C, +60 °C

## Construction

- Current-compensated double choke
- Closed rectangular ferrite core
- Closed plastic coil former (UL 94 V-0)<sup>1</sup>)
- Without encapsulation
- 2-section winding
- Clearance and creepage distances ≥ 3 mm

### **Features**

- High resonance frequency due to 2-section winding
- Approx. 0.55% stray inductance for symmetrical interference suppression
- Low leakage due to closed core shape
- High pulse strength
- Low whirring noise
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2) and UL 1283
- Recyclable owing to omission of encapsulation and glue
- RoHS-compatible

#### **Applications**

- Suppression of common-mode interferences
- Switch-mode power applications
- Electronic ballasts in lamps

### **Terminals**

- Base material CuNi18Zn20
- Layer composition Ni, Sn
- Hot-dipped
- Pins 0.7 × 0.7 (mm)
- Lead spacing 15 × 12.5 (mm)

#### Marking

Manufacturer, rated inductance, rated current, ordering code, approval symbols, date of manufacture (WWYY)

## **Delivery mode**

Blister tray in cardboard box

1) Additionally certified values: Glow wire flammability index (GWFI to IEC 60695-2-12): +850 °C Glow wire ignition temperature (GWIT to IEC 60695-2-13): +775 °C Glow wire test (GWT to IEC 60695-2-11): Comparative tracking index (CTI to IEC 60112): 175 V Ball pressure test (BP to IEC 60695-10-2): +125 °C 2) UL approval with 300 V AC.

Please read Cautions and warnings and Important notes at the end of this document. +750 °C, 2 s / 850 °C, 30 s

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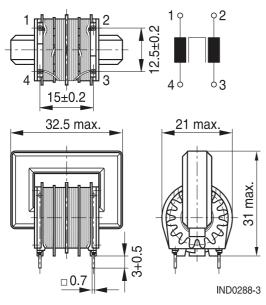






# Dimensional drawings and pin configurations

Vertical version (B82734R)



Horizontal version (B82734W)

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# Technical data and measuring conditions

Rated voltage V <sub>R</sub>	250 V AC (50/60 Hz)
Test voltage V <sub>test</sub>	1500 V AC, 2 s (line/line)
Rated temperature T <sub>R</sub>	+40 °C / +60 °C
Rated current I <sub>R</sub>	Referred to 50 Hz and rated temperature
Rated inductance L <sub>R</sub>	Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C Inductance is specified per winding.
Inductance tolerance	–30%/+50% at +20°C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I <sub>R</sub> , +20 °C
Stray inductance L <sub>stray,typ</sub>	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typ. values
DC resistance R <sub>typ</sub>	Measured at +20 °C, typical values, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 $\pm$ 3) °C, (3 $\pm$ 0.3) s Wetting of soldering area $\geq$ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat	+(260 ±5) °C, (10 ±1) s
(wave soldering)	(to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)

# **Characteristics and ordering codes**

× = approval granted

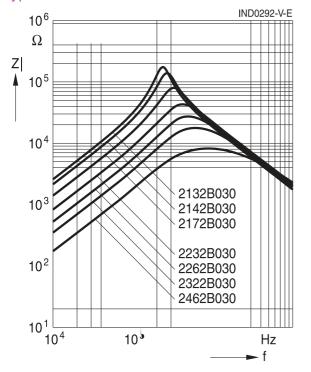
Please read *Cautions and warnings* and *Important notes* at the end of this document.





# **Impedance |Z| versus frequency f** measured with windings in parallel at +20 °C

typical values



Current derating  $I_{op}/I_R$  versus ambient temperature  $T_A$ 



## **Cautions and warnings**

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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